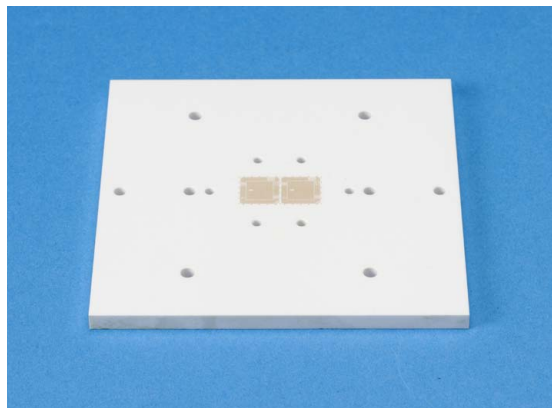
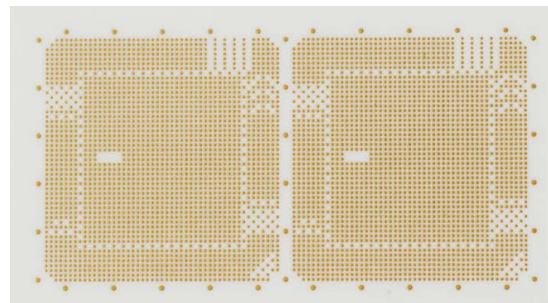


LTCC Interposer Substrate



90x90x4.5mm

Enlarged DUT Pattern



Approx. 5,000 pads, 200μm pitch

Application

Interposer substrates for semiconductor wafer test probe card.*

*LTCC Interposer Substrate

Thousands of bonding pads are densely packed onto an LSI semiconductor wafer. Testing of LSI semiconductor wafers cannot be performed without a probe card, because the fine-pitch bonding pads need to be expanded spatially by the probe card to be connectable to the tester. The LTCC interposer substrate is a key component of a probe card.

Features

- Low-resistance silver-paste lines and via holes are configured three-dimensionally on a multilayer substrate consisting of all LTCC layers. This permits the substrate to be compatible with area-array-type probe cards with fine pitch and ultra-high pin count. Thanks to the use of high frequency technologies, the substrate is also suitable for probe cards for testing high-frequency devices.

•Pogo pins Connected Type

